CLAIMS

1. A chemically amplified positive photosensitive thermosetting resin composition comprising a reaction product of (A) an alkali soluble resin and (C) a crosslinking polyvinyl ether compound, (B) a compound generating an acid under irradiation with radiation, and (D) an epoxy resin.

2. A chemically amplified positive photosensitive thermosetting resin composition comprising (A) an alkali soluble resin, (B) a compound generating an acid under irradiation with radiation, (C) a crosslinking polyvinyl ether compound, and (D) an epoxy resin.

3. The chemically amplified positive photosensitive thermosetting resin composition according to claim 1, which comprises a curing accelerator for the component (D).

4. The chemically amplified positive photosensitive thermosetting resin composition according to claim 3, wherein the curing accelerator is a basic compound.

5. The chemically amplified positive photosensitive thermosetting resin composition according to claim 2, which comprises a curing accelerator for the component (D).

6. The chemically amplified positive photosensitive thermosetting resin composition according to claim 5, wherein the curing accelerator is a basic compound.

7. A method for formation of a cured article, which comprises applying the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6, subjecting to prebaking, subjecting to selective exposure, subjecting to PEB (post-exposure baking) and subjecting to alkali development to form a resist pattern, followed by melting with heating and further heat curing.

8. A cured article obtainable by the method of claim 7.

9. A method for production of a functional device, which comprises forming a resist pattern of and curing the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6.

10. A functional device obtainable by the method of claim 9.